

# BENEQ C2R



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## Rotary batch PEALD

- High dep rate: 1–2  $\mu\text{m}/\text{hour}$
- Typical uniformity < 2 % over the batch
- Typical materials  $\text{SiO}_2$ ,  $\text{TiO}_2$ ,  $\text{Ta}_2\text{O}_5$ ,  $\text{Al}_2\text{O}_3$
- Single-side coating
- Optional wafer automation
- Typical substrates:
  - Wafers, up to 200 mm
  - Windows
  - High curvature lenses (dia 1...20 mm)
  - Dies on carrier

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## PROCESS TYPE

- rotary spatial plasma enhanced ALD
- single side coating

## USAGE

- production

## SUBSTRATE TYPE

- up to 200 mm wafer

## SUBSTRATE LOADING

- automatic
- manual

## MAIN DIMENSIONS

- 1720x1340x1280 mm

## INTEGRATION

- cluster

For product inquiries, please contact:

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Technical information in this document is subject to change without notice. 3/2021

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